

## P-Channel 100 V (D-S) MOSFET

PRODUCT SUMMARY			
$V_{DS}$ (V)	$R_{DS(on)}$ ( $\Omega$ ) Max.	$I_D$ (A) <sup>c</sup>	$Q_g$ (Typ.)
- 100	0.138 at $V_{GS} = - 10$ V	- 16.3	24 nC
	0.141 at $V_{GS} = - 7.5$ V	- 16.1	
	0.142 at $V_{GS} = - 6$ V	- 16.1	

### FEATURES

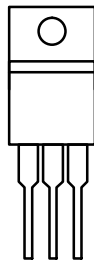
- TrenchFET<sup>®</sup> Power MOSFET
- 100 %  $R_g$  and UIS Tested
- Material categorization:  
For definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)



**RoHS**  
COMPLIANT  
HALOGEN  
**FREE**

### APPLICATIONS

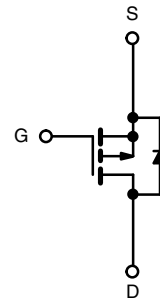
- DC/DC Converters
- Motor Control

**TO-220AB**

 G D S  
Top View

Drain connected to Tab

**Ordering Information:**

SUP25P10-138-GE3 (Lead (Pb)-free and Halogen-free)



P-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS ( $T_C = 25$ °C, unless otherwise noted)			
Parameter	Symbol	Limit	Unit
Drain-Source Voltage	$V_{DS}$	- 100	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	
Continuous Drain Current ( $T_J = 150$ °C)	$T_C = 25$ °C	- 16.3	A
	$T_C = 125$ °C	- 7.3	
Pulsed Drain Current ( $t = 100$ $\mu$ s)	$I_{DM}$	- 40	
Avalanche Current	$I_{AS}$	- 25	mJ
Single Pulse Avalanche Energy <sup>a</sup>	$E_{AS}$	31.25	
Power Dissipation	$T_C = 25$ °C	73.5 <sup>b</sup>	W
	$T_A = 25$ °C	3.1	
Operating Junction and Storage Temperature Range	$T_J, T_{stg}$	- 55 to 150	°C

THERMAL RESISTANCE RATINGS			
Parameter	Symbol	Limit	Unit
Junction-to-Ambient Free Air	$R_{thJA}$	40	°C/W
Junction-to-Case	$R_{thJC}$	1.7	

**Notes:**

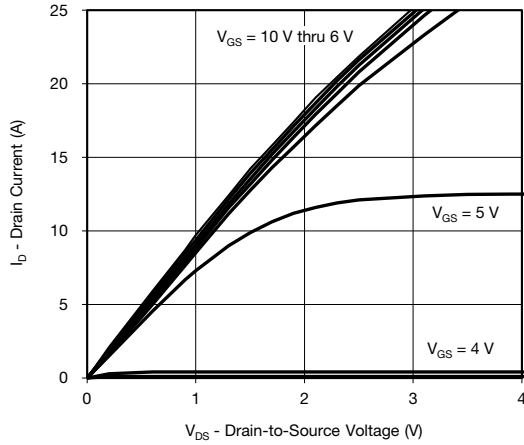
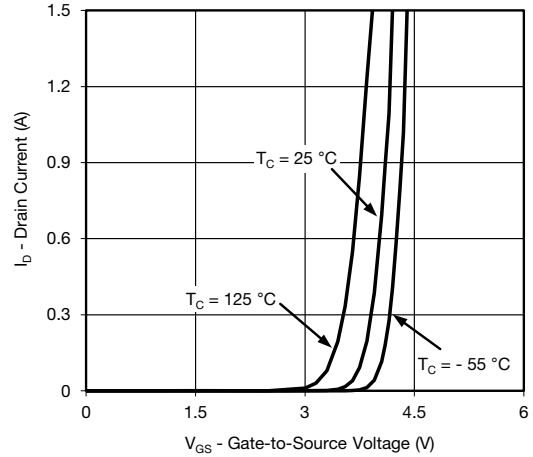
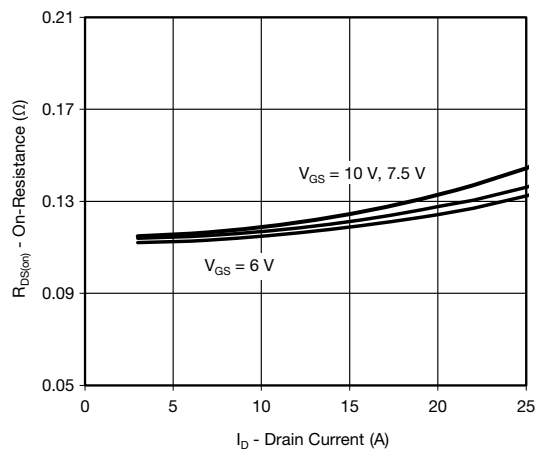
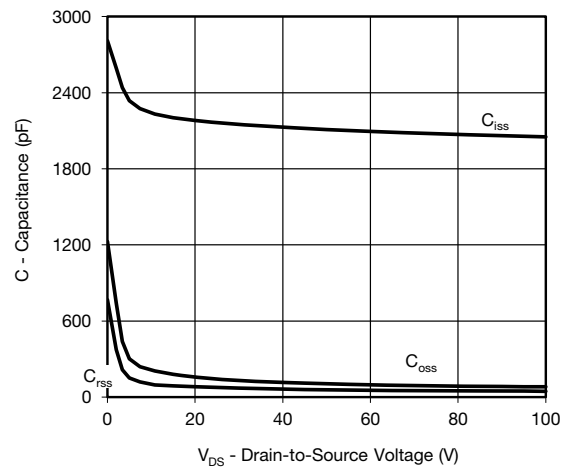
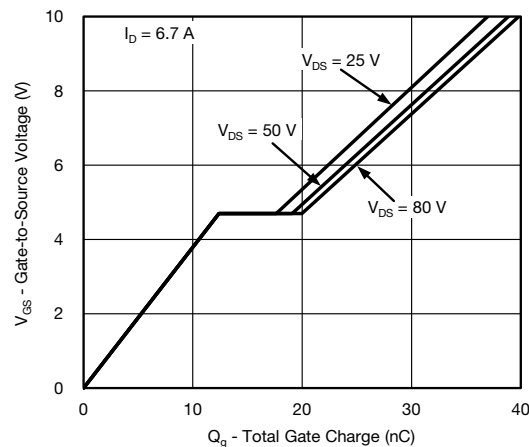
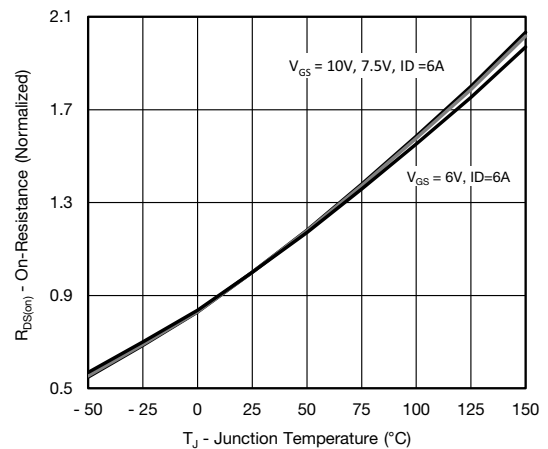
- Duty cycle  $\leq 1$  %.
- See SOA curve for voltage derating.
- $T_C = 25$  °C

SPECIFICATIONS ( $T_J = 25\text{ }^\circ\text{C}$ , unless otherwise noted)						
Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
<b>Static</b>						
Drain-Source Breakdown Voltage	$V_{DS}$	$V_{GS} = 0\text{ V}, I_D = -250\text{ }\mu\text{A}$	-100			V
Gate-Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = -250\text{ }\mu\text{A}$	-2		-4	
$V_{DS}$ Temperature Coefficient	$\Delta V_{DS}/T_J$	$I_D = -250\text{ }\mu\text{A}$		-105		mV/ $^\circ\text{C}$
$V_{GS(th)}$ Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	$I_D = -250\text{ }\mu\text{A}$		6.6		
Gate-Body Leakage	$I_{GSS}$	$V_{DS} = 0\text{ V}, V_{GS} = \pm 20\text{ V}$			$\pm 100$	nA
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = -100\text{ V}, V_{GS} = 0\text{ V}$			-1	$\mu\text{A}$
		$V_{DS} = -100\text{ V}, V_{GS} = 0\text{ V}, T_J = 125\text{ }^\circ\text{C}$			-50	
		$V_{DS} = -100\text{ V}, V_{GS} = 0\text{ V}, T_J = 150\text{ }^\circ\text{C}$			-200	
On-State Drain Current <sup>a</sup>	$I_{D(on)}$	$V_{DS} = -5\text{ V}, V_{GS} = -10\text{ V}$	-20			A
Drain-Source On-State Resistance <sup>a</sup>	$R_{DS(on)}$	$V_{GS} = -10\text{ V}, I_D = -6\text{ A}$		0.115	0.138	$\Omega$
		$V_{GS} = -7.5\text{ V}, I_D = -6\text{ A}$		0.117	0.141	
		$V_{GS} = -6\text{ V}, I_D = -6\text{ A}$		0.118	0.142	
Forward Transconductance <sup>a</sup>	$g_{fs}$	$V_{DS} = -15\text{ V}, I_D = -6\text{ A}$		18		S
<b>Dynamic<sup>b</sup></b>						
Input Capacitance	$C_{iss}$	$V_{GS} = 0\text{ V}, V_{DS} = -50\text{ V}, f = 1\text{ MHz}$		2110		$\mu\text{F}$
Output Capacitance	$C_{oss}$			105		
Reverse Transfer Capacitance	$C_{rss}$			58		
Total Gate Charge <sup>c</sup>	$Q_g$	$V_{DS} = -50\text{ V}, V_{GS} = -10\text{ V}, I_D = -6.7\text{ A}$		40	60	nC
		$V_{DS} = -50\text{ V}, V_{GS} = -6\text{ V}, I_D = -6.7\text{ A}$		24	36	
Gate-Source Charge <sup>c</sup>	$Q_{gs}$	$V_{DS} = -50\text{ V}, V_{GS} = -6\text{ V}, I_D = -6.7\text{ A}$		12.5		
Gate-Drain Charge <sup>c</sup>	$Q_{gd}$	$V_{DS} = -50\text{ V}, V_{GS} = -6\text{ V}, I_D = -6.7\text{ A}$		6.7		
Gate Resistance	$R_g$	$f = 1\text{ MHz}$	2	8	16	$\Omega$
Turn-On Delay Time <sup>c</sup>	$t_{d(on)}$	$V_{DD} = -50\text{ V}, R_L = 10\text{ }\Omega$ $I_D \cong -5\text{ A}, V_{GEN} = -10\text{ V}, R_g = 1\text{ }\Omega$		7	14	ns
Rise Time <sup>c</sup>	$t_r$			12	20	
Turn-Off Delay Time <sup>c</sup>	$t_{d(off)}$			46	70	
Fall Time <sup>c</sup>	$t_f$			40	60	
Turn-On Delay Time <sup>c</sup>	$t_{d(on)}$	$V_{DD} = -50\text{ V}, R_L = 10\text{ }\Omega$ $I_D \cong -5\text{ A}, V_{GEN} = -4.5\text{ V}, R_g = 1\text{ }\Omega$		12	20	
Rise Time <sup>c</sup>	$t_r$			105	160	
Turn-Off Delay Time <sup>c</sup>	$t_{d(off)}$			36	54	
Fall Time <sup>c</sup>	$t_f$			34	51	
<b>Source-Drain Diode Ratings and Characteristics <math>T_C = 25\text{ }^\circ\text{C}</math><sup>b</sup></b>						
Continuous Current	$I_S$				-16.3	A
Pulsed Current ( $t = 100\text{ }\mu\text{s}$ )	$I_{SM}$				-40	
Forward Voltage <sup>a</sup>	$V_{SD}$	$I_F = -5\text{ A}, V_{GS} = 0\text{ V}$		-0.85	-1.5	V
Reverse Recovery Time	$t_{rr}$	$I_F = -5\text{ A}, di/dt = 100\text{ A}/\mu\text{s}$		70	105	ns
Peak Reverse Recovery Current	$I_{RM(REC)}$			-7	-14	A
Reverse Recovery Charge	$Q_{rr}$				220	330

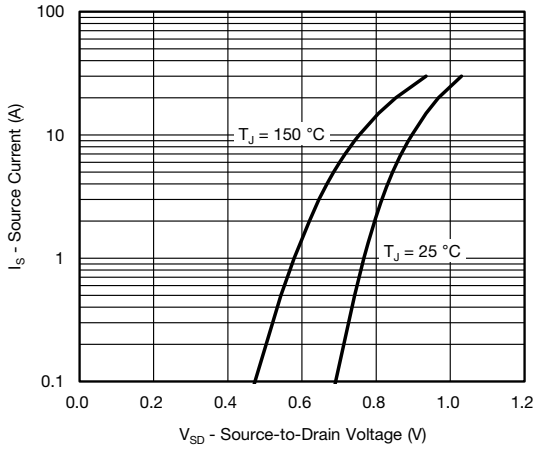
Notes:

- a. Pulse test; pulse width  $\leq 300\text{ }\mu\text{s}$ , duty cycle  $\leq 2\%$ .
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

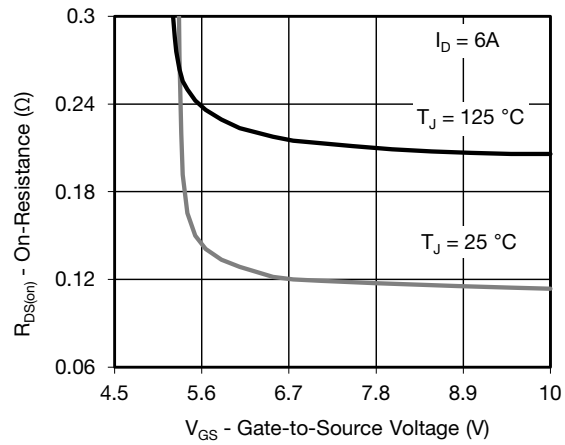
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

**TYPICAL CHARACTERISTICS** (25 °C, unless otherwise noted)

**Output Characteristics**

**Transfer Characteristics**

**On-Resistance vs. Drain Current and Gate Voltage**

**Capacitance**

**Gate Charge**

**On-Resistance vs. Junction Temperature**

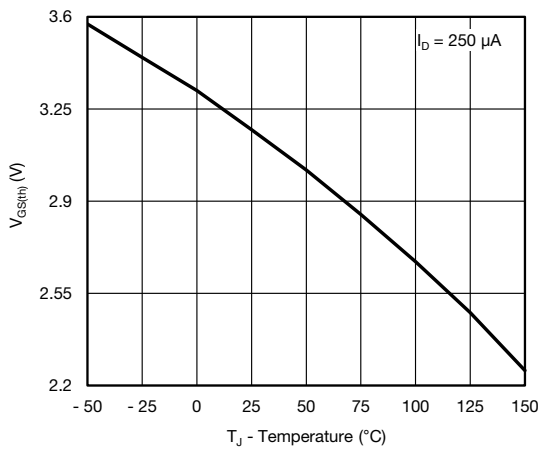
## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



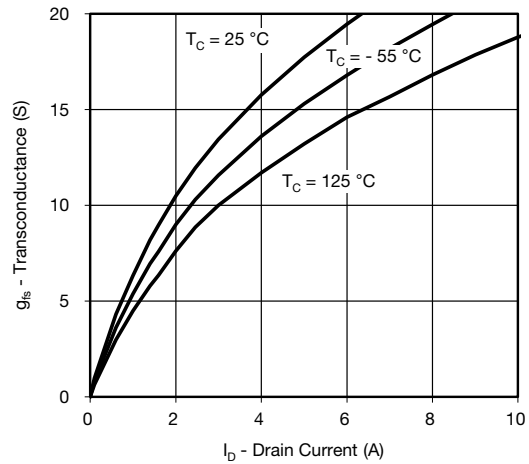
Source-Drain Diode Forward Voltage



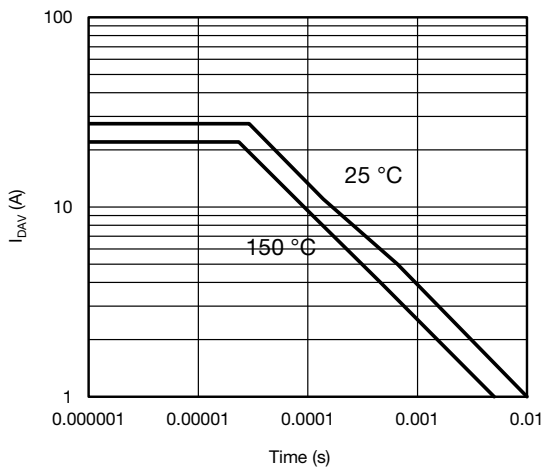
On-Resistance vs. Gate-to-Source Voltage



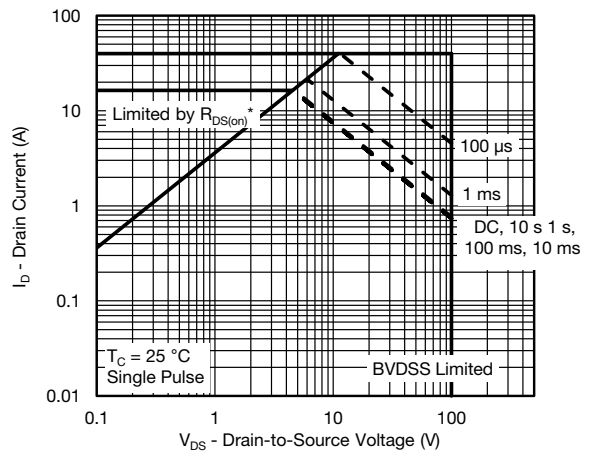
Threshold Voltage



Transconductance

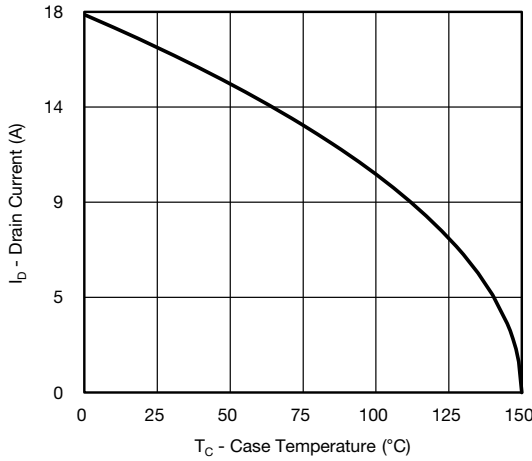


Single Pulse Avalanche Capability

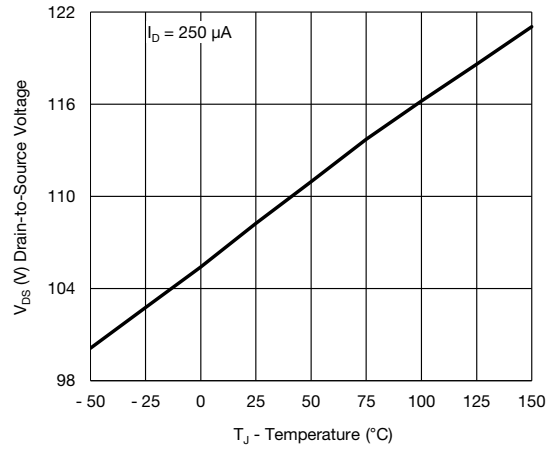


Safe Operating Area, Junction-to-Case

**TYPICAL CHARACTERISTICS** (25 °C, unless otherwise noted)

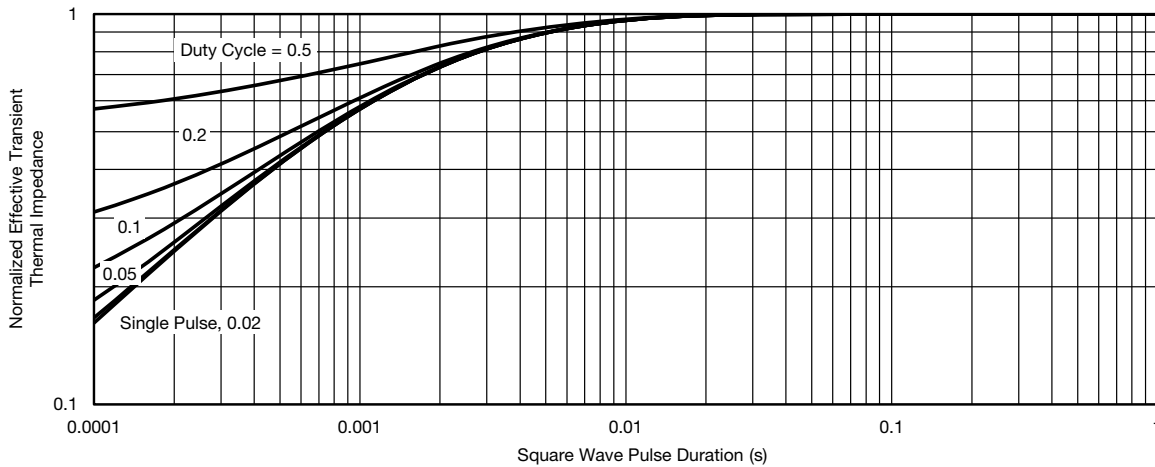


**Current Derating\***



**Drain Source Breakdown vs. Junction Temperature**

\* The power dissipation P<sub>D</sub> is based on T<sub>J(max.)</sub> = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.



**Normalized Thermal Transient Impedance, Junction-to-Case**

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